Synopsys Design Vision EDA tool

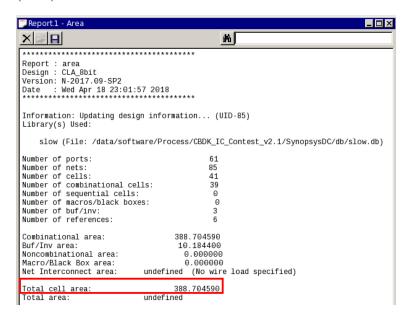
范真瑋

合成步驟:

- 1. 設置.synopsys_dc.setup
- 2. 使用指令 dv 調用 design compiler
- 3. 檢查 Library 是否正確載入
- 4. 讀取檔案
- 5. 選擇 TOP module current_design CLA_8bit
- 6. hux Buffer set_fix_multiple_port_nets -all -buffer_constants
- 7. 移除空接腳位 remove unconnected ports -blast buses [get cells * -hier]
- 8. Design→Compile Design
- 9. 查看 Area、Timing、Power Report、Critical Path
- 10. 儲存電路(CLA_syn.v)與.sdf 檔案 write_sdf -version 1.0 -context verilog CLA.sdf
- 11. 修改 testbench
- 12. 在 CLA syn.v 中加入與 testbench 相同的`timescale
- 13. 輸入指令進行模擬 ncverilog CLA_tb.v +access+r
- 14. 使用 SimVision 觀察波型

Gate count:

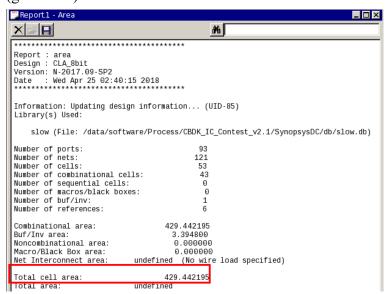
(RTL)



Gate count = reported area / area of a NAND2 gate

Area of a NAND2 gate is approximately 5 um x um for 0.13um technology 此設計的面積為 388.705 um x um,因此 gate count 約為 78。

(gate level)



此設計的面積為 429.442 um x um, 因此 gate count 約為 86。

Critical path delay:

(RTL)

Operating Conditions: slow Library: slow Wire Load Model Mode: top Startpoint: B[0] (input port)
Endpoint: C_out (output port)
Path Group: (none)
Path Type: max Point Path Incr Point

input external delay
B[0] (in)
U20/Y (XNOR2X1)
CLA4_1/B[0] (CLA_4bit_1)
CLA4_1/VI14/Y (XOR2X1)
CLA4_1/VI13/Y (AO22X1)
CLA4_1/VI13/Y (AO22X1)
CLA4_1/VI17/Y (AO122X1)
CLA4_1/VI17/Y (AO122X1)
CLA4_1/C_out[3] (CLA_4bit_1)
CLA4_2/C_oin (CLA_4bit_0)
CLA4_2/VI13/Y (AO22X1)
CLA4_2/VI17/Y (AO122X1)
CLA4_2/U31/Y (AO122X1)
CLA4_2/U5/Y (AO22X1)
CLA4_2/U5/Y (AO22X1)
CLA4_2/C_out[3] (CLA_4bit_0)
U21/Y (OR2X1)
C_out (out)
data arrival time 0.00 0.00 0.14 0.00 0.20 0.36 0.22 0.14 0.00 r 0.00 r 0.14 r 0.14 r 0.34 f 0.70 f 0.92 r 1.05 f 1.34 f 1.34 f 1.34 f 1.72 f 1.94 r 2.10 f 2.40 f 2.60 f 2.60 f 0.00 0.00 0.37 0.22 0.17 0.30 0.00 0.20 0.00 (Path is unconstrained)



Timing Report 中,Incr 為節點造成的延遲時間,Path 為 Path 起點到此節點的總 延遲時間,可以知道 critical path 為 B[0]到 C_out (如同 Schematic 圖),且 delay 為 2.60 ns。

(gate level)

Operating Conditions: slow Wire Load Model Mode: top Library: slow

Startpoint: B[0] (input port) Endpoint: C_out (output port) Path Group: (none) Path Type: max

Point	Incr	
Point input external delay B[0] (in) U20/Y (XNOR2X1) CLA4_1/B[0] (CLA_4bit_1) CLA4_1/HA0/y (half_adder_7) CLA4_1/HA0/U1/Y (XOR2X1) CLA4_1/HA0/Sum (half_adder_7) CLA4_1/U8/Y (A021X1) CLA4_1/U7/Y (A021X1) CLA4_1/U5/Y (A021X1) CLA4_1/U5/Y (A021X1) CLA4_1/U5/Y (A021X1) CLA4_1/U5/Y (A021X1) CLA4_1/C_out[3] (CLA_4bit_1) CLA4_2/U5/Y (A021X1) CLA4_2/C_out[3] (CLA_4bit_0) U21/Y (OR2X1)	0.00 0.00 0.14 0.00 0.20 0.00 0.28 0.29 0.29 0.29 0.00 0.00 0.29	0.00 r 0.00 r 0.14 r 0.14 r 0.14 r 0.34 f 0.62 f 0.91 f 1.50 f 1.50 f 1.50 f 1.79 f 2.70 f 2.70 f
C_out (out) data arrival time	0.00	2.90 f 2.90
(Path is unconstrained)		



可知 critical path 為 B[0]到 C_out (如同 Schematic 圖),且 delay 為 2.90 ns。

Power consumption:

(RTL)

```
🌅 Report.3 - Power
                                                                                                                           _ 🗆 ×
                                                                      #6
XB
                                                                                                                                 _
Library(s) Used:
     slow (File: /data/software/Process/CBDK_IC_Contest_v2.1/SynopsysDC/db/slow.db)
Operating Conditions: slow Library: slow Wire Load Model Mode: top
Global Operating Voltage = 1.08
Power-specific unit information :
Voltage Units = 1V
     Capacitance Units = 1.000000pf
     Time Units = 1ns
Dynamic Power Units = 1mW
Leakage Power Units = 1pW
                                         (derived from V,C,T units)
  Cell Internal Power = 53.0117 uW
Net Switching Power = 17.0181 uW
                                                 (76\%)
Total Dynamic Power
                            = 70.0299 uW (100%)
Cell Leakage Power
                            = 465.0521 nW
```

從 Power Report 中得知,Dynamic power 為 70.0299 uW,Static power 為 465.0521 nW。

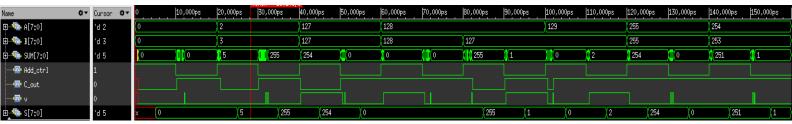
(gate level)

```
🌅 Report.3 - Powei
                                                                         86
                                                                                                                                     •
 Library(s) Used:
      slow (File: /data/software/Process/CBDK_IC_Contest_v2.1/SynopsysDC/db/slow.db)
 Operating Conditions: slow
Wire Load Model Mode: top
                                     Library: slow
 Global Operating Voltage = 1.08
 Power-specific unit information :
Voltage Units = 1V
      Capacitance Units = 1.000000pf
      Time Units = 1ns
Dynamic Power Units = 1mW
Leakage Power Units = 1pW
                                            (derived from V, C, T units)
   Cell Internal Power = 56.1834 uW
Net Switching Power = 15.2171 uW
                                                   (79%)
(21%)
                              = 71.4004 uW (100%)
 Total Dynamic Power
 Cell Leakage Power
                               = 585.3405 nW
```

得知 Dynamic power 為 71.4004 uW, Static power 為 585.3405 nW。

结果分析:

(RTL 合成後的模擬結果)

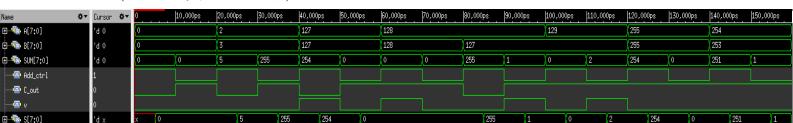


波形圖中左側的 A 與 B 均為 8-bit binary 輸入,SUM 為 8-bit 輸出,Add_ctrl 為 1-bit 輸入選擇做加法或減法, C_{out} 為 1-bit carry out 輸出,V 為 1-bit overflow 輸出,V 為 testbench 中用來檢查運算結果是否正確的變數。Add_ctrl=1 做加法 運算,Add_ctrl=0 做減法運算。測試的資料有邊界值、正常數值,各挑選正數 與負數做加法與減法,因為資料以 8-bit 表示,數值範圍是-128~127,因此做加減法後,數值過大或過小都會造成 overflow,使 V 變為 V 多

ncsim> run							
	5ns	0	+	0	=	0	(correct)
	15ns	0		0	=	0	(correct)
	25ns	2	+	3	=	5	(correct)
	35ns	2		3	=	-1	(correct)
	45ns	127	+	127	=	-2	(correct) (overflow)
	55ns	127		127	=	0	(correct)
	65ns	-128	+	-128	=	0	(correct) (overflow)
	75ns	-128		-128	=	0	(correct)
	85ns	-128	+	127	=	-1	(correct)
	95ns	-128		127	=	1	(correct) (overflow)
	105ns	-127	+	127	=	0	(correct)
	115ns	-127		127	=	2	(correct) (overflow)
	125ns	-1	+	-1	=	-2	(correct)
	135ns	-1		-1	=	0	(correct)
	145ns	-2	+	-3	=	-5	(correct)
	155ns	-2		-3	=	1	(correct)
Simulation compl	lete via	\$finish	h(1)	at t	ime	160	NS + 0
./CLA_tb.v:158 #5 \$finish;							
ncsim> exit							
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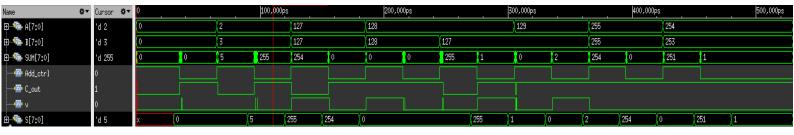
經模擬與親自驗證結果皆正確。

(RTL 合成前的模擬結果)

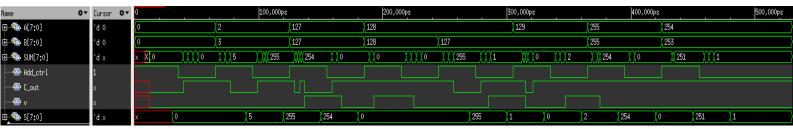


與合成前的結果相比,可發現合成後多了 delay,因為原本沒有設定 gate delay,而合成時使用了 tsmc13 製程,來模擬實際情況,因此可看到輸出結果時會有 delay。

(gate level 合成後的模擬結果)



(gate level 作業一的模擬結果)



然而因為作業一的 gate level 就有使用 gate delay,因此合成前後的波形圖差不多,不過作業一的 gate delay 是自己訂的,而這次作業的 delay 為 tsmc13 製程的 delay。相比之下,作業一的 gate delay 較久,較晚得到運算結果。